AMENDMENTS TO THE CLAIMS

This listing of claims replaces all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

Claims 1-8 (canceled).

Claim 9 (previously presented): A multilayered printed circuit board comprising:

a conductor circuit and a resin insulating layer serially formed on a substrate in an alternate fashion and in repetition; and a solder resist layer formed as an outermost layer,

wherein said solder resist layer contains an elastomer component in a composition comprising a resin for said solder resist layer, and

said elastomer component is separated in micro-phase as to form an island-in-sea structure after curing in said solder resist layer.

Claims 10-30 (canceled).

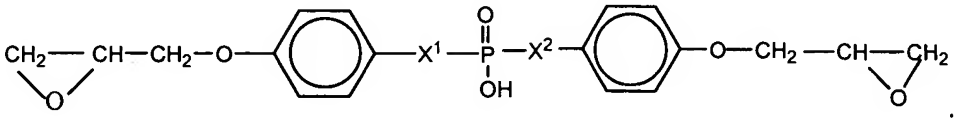
Claim 31 (currently amended): A multilayered printed circuit board comprising: a conductor circuit and a resin insulating layer serially formed on a substrate in an alternate fashion and in repetition; and a solder resist layer formed as an outermost layer,

wherein said solder resist layer contains a P atom-containing epoxy resin, and

said P atom-containing epoxy ~~resins~~ resin has bivalent phosphoric acid residue, and has epoxy groups in both terminals of the P atom-containing epoxy resin.

Claim 32 (original): The multilayered printed circuit board according to claim 31,

wherein said epoxy resin having bivalent phosphoric acid residue and having epoxy groups in both terminals is an epoxy resin having the following general formula [4]



. . .(4)

(wherein X^1, X^2 respectively represent O or a single bond).

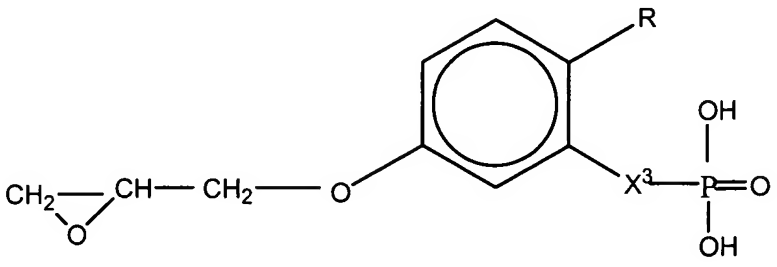
Claim 33 (currently amended): A multilayered printed circuit board comprising: a conductor circuit and a resin insulating layer serially formed on a substrate in an alternate fashion ~~an d~~ and in repetition; and a solder resist layer formed as an outermost layer,

wherein said solder resist layer contains a P atom-containing epoxy resin, and

said P atom-containing epoxy resin is an epoxy resin having a monovalent phosphoric acid residue in one terminal of the P atom-containing epoxy resin and an epoxy group in the other terminal of the P atom-containing epoxy resin.

Claim 34 (previously presented): The multilayered printed circuit board according to claim 33,

wherein said epoxy resin having a monovalent phosphoric acid residue in one terminal and an epoxy group in the other terminal is an epoxy resin having the following general formula [5]:



. . . (5)

(wherein X^3 represents O or a single bond; and R represents an alkyl of 2 to 8 carbons).

Claim 35 (canceled).

Claim 36 (previously presented): A multilayered printed circuit board comprising:

a conductor circuit and a resin insulating layer serially formed on a substrate in an alternate fashion and in repetition; and a solder resist layer formed as an outermost layer,

wherein said solder resist layer contains an elastomer component in a composition comprising a resin for said solder resist layer,

said elastomer component is at least one member selected from the group consisting of natural rubber, synthetic rubber, a thermoplastic resin and a thermosetting resin, and

said elastomer component is separated in micro-phase as to form an island-in-sea structure after curing in said solder resist layer.

Claim 37 (new): The multilayered printed circuit board according to claim 31,

wherein said solder resist layer contains at least one member selected from the group consisting of a silicon compound, an aluminum compound and a magnesium compound.

Claim 38 (new): The multilayered printed circuit board according to claim 33,

wherein said solder resist layer contains at least one member selected from the group consisting of a silicon compound, an aluminum compound and a magnesium compound.